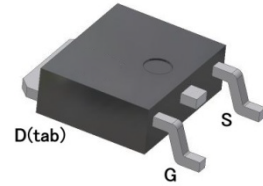
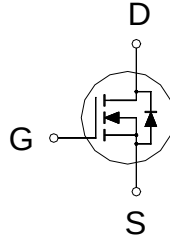


N-Channel Logic Level Enhancement Mode Field Effect Transistor

Product Summary:

BV _{DSS}	60V
R _{DS(on)} (MAX.)	45mΩ
I _D	18A



UIS, R_g 100% Tested

Pb-Free Lead Plating & Halogen Free



ABSOLUTE MAXIMUM RATINGS (T_C = 25 °C Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		V _{GS}	±20	V
Continuous Drain Current	T _C = 25 °C	I _D	18	A
	T _C = 100 °C		12	
Pulsed Drain Current ¹		I _{DM}	50	
Avalanche Current		I _{AS}	15	
Avalanche Energy	L = 0.1mH, I _D =15A, R _G =25Ω	E _{AS}	11.25	mJ
Repetitive Avalanche Energy ²	L = 0.05mH	E _{AR}	5.6	
Power Dissipation	T _C = 25 °C	P _D	33	W
	T _C = 100 °C		13.5	
Operating Junction & Storage Temperature Range		T _j , T _{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	R _{θJC}		3.7	°C / W
Junction-to-Ambient	R _{θJA}		80	

¹Pulse width limited by maximum junction temperature.

²Duty cycle ≤ 1%

ELECTRICAL CHARACTERISTICS (T_c = 25 °C, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	60			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1.0	2.0	3.2	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 48V, V _{GS} = 0V			1	μA
		V _{DS} = 40V, V _{GS} = 0V, T _J = 125 °C			25	
On-State Drain Current ¹	I _{D(ON)}	V _{DS} = 10V, V _{GS} = 10V	18			A
Drain-Source On-State Resistance ¹	R _{DS(ON)}	V _{GS} = 10V, I _D = 13A		41	45	mΩ
		V _{GS} = 5V, I _D = 8A		60	70	
Forward Transconductance ¹	g _{fs}	V _{DS} = 5V, I _D = 10A		15		S
DYNAMIC						
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = 30V, f = 1MHz		945		pF
Output Capacitance	C _{oss}			81		
Reverse Transfer Capacitance	C _{rss}			56		
Gate Resistance	R _g	V _{GS} = 15mV, V _{DS} = 0V, f = 1MHz		2.0		Ω
Total Gate Charge ^{1,2}	Q _g	V _{DS} = 30V, V _{GS} = 10V, I _D = 10A		18		nC
Gate-Source Charge ^{1,2}	Q _{gs}			3.3		
Gate-Drain Charge ^{1,2}	Q _{gd}			5.1		
Turn-On Delay Time ^{1,2}	t _{d(on)}	V _{DS} = 20V, I _D = 1A, V _{GS} = 10V, R _{GS} = 6Ω		12		nS
Rise Time ^{1,2}	t _r			8		
Turn-Off Delay Time ^{1,2}	t _{d(off)}			20		
Fall Time ^{1,2}	t _f			7		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T _C = 25 °C)						
Continuous Current	I _S				18	A
Pulsed Current ³	I _{SM}				50	
Forward Voltage ¹	V _{SD}	I _F = 13A, V _{GS} = 0V			1.3	V
Reverse Recovery Time	t _{rr}	I _F = 5A, dI _F /dt = 100A / μS		32		nS
Reverse Recovery Charge	Q _{rr}			37		nC

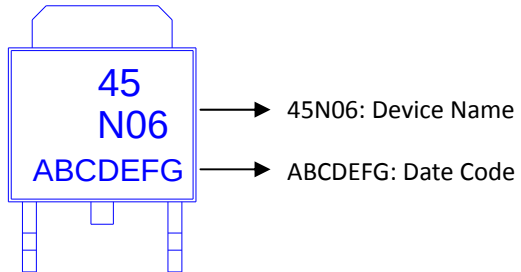
¹Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

²Independent of operating temperature.

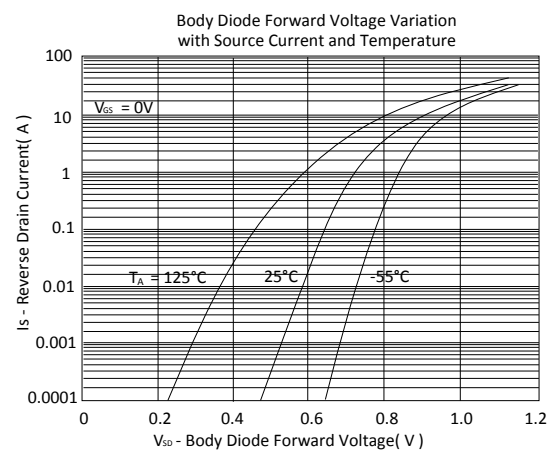
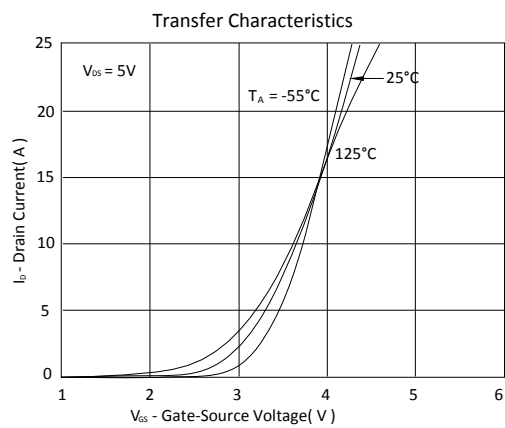
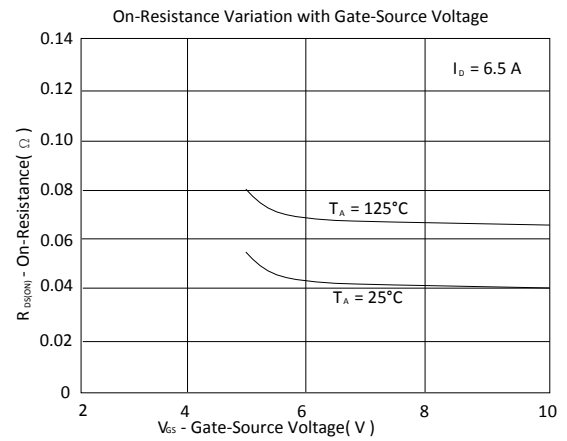
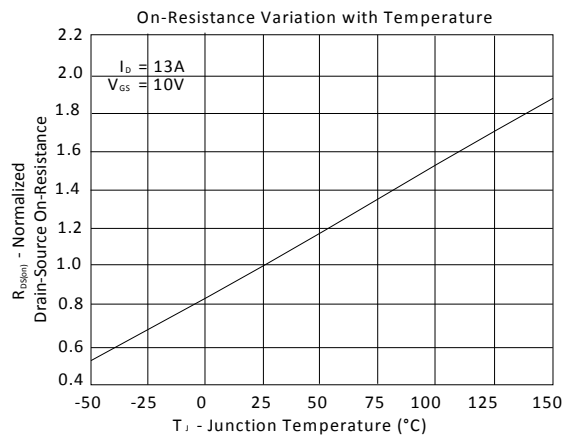
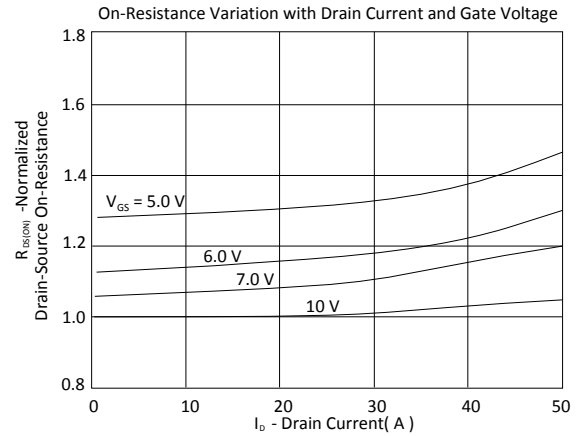
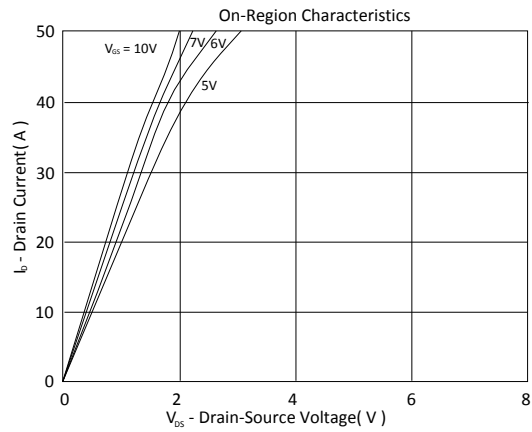
³Pulse width limited by maximum junction temperature.

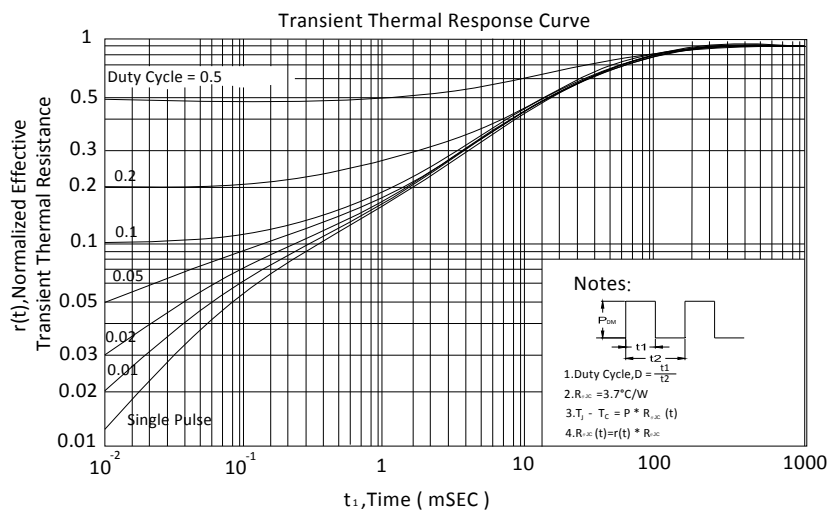
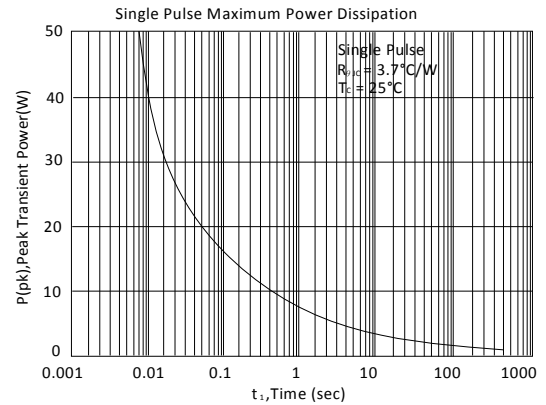
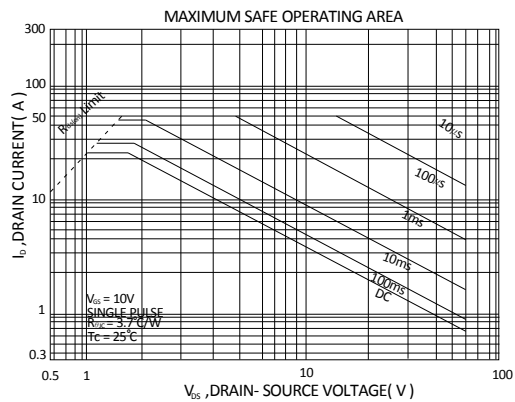
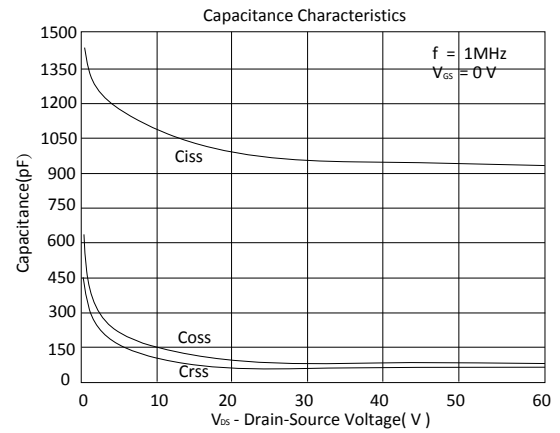
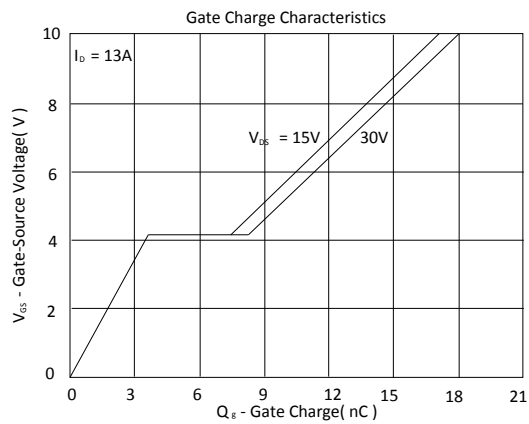
Ordering & Marking Information:

Device Name: LB45N06D for DPAK (TO-252)

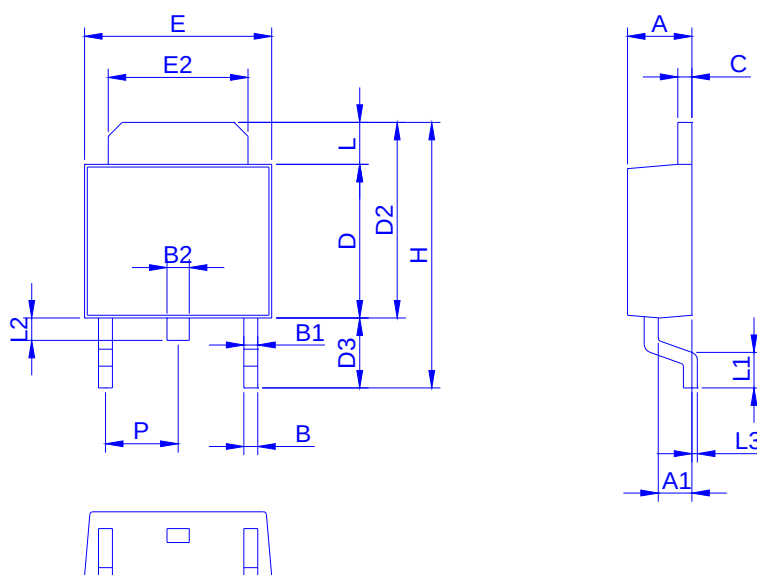


TYPICAL CHARACTERISTICS





Outline Drawing



Dimension	A	A1	B	B1	B2	C	D	D2	D3	E	E2	H	L	L1	L2	L3	P
Min.	2.10	0.95	0.30	0.40	0.60	0.40	5.30	6.70	2.20	6.40	4.80	9.20	0.89	0.90	0.50	0.00	2.10
Max.	2.50	1.30	0.85	0.94	1.00	0.60	6.20	7.30	3.00	6.70	5.45	10.15	1.70	1.65	1.10	0.30	2.50

Footprint

